

Amendments to the Claims

Claim 1 (currently amended). A susceptor for supporting a semiconductor wafer having a diameter of at least 300mm and a perimeter edge, the susceptor comprising:

a surface for supporting the semiconductor wafer, said surface having a concave ~~shape~~ shaped surface area, said surface area ~~and~~ being configured to cause the semiconductor wafer to contact said surface area at the perimeter edge only, said surface having a center portion and an outer portion surrounding said center portion, defining a distance between said center portion and a plane defined by a circle along said outer portion, said circle having a diameter of substantially 300mm and said distance being greater than ~~500um~~ 500um; and

a heater thermally coupled to said surface for heating said surface.

Claims 2-4 (canceled).

Claim 5 (original). The susceptor according to claim 1, wherein said susceptor is formed of metal.

Claim 6 (original). The susceptor according to claim 1, wherein said heater is configured to heat the wafer to a temperature of at least 400°C.

Claim 7 (canceled).

Claim 8 (original). The susceptor according to claim 1, wherein said surface is formed with a plurality of concentric, projecting rings.